
september 23 - 24, 1999

bulk feeding summit

northbrook, il
hilton hotel

For Component Manufacturers, Equipment
Manufacturers, Original Equipment Manufacturers,
Electronics Manufacturing Services Companies:

The opportunities and barriers to bulk feeding for
pick and place equipment.



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES

Bulk Feeding:

Is it the future of high volume placement of surface mount components?

Bulk feeding of surface mount components for pick and place machines offers a number of appealing features. With bulk feeding, according to users:

- The process is friendly to the environment. Because there's no tape and reel, there's no tape waste disposal. And there's no paper dust for a cleaner machine environment.
- Material handling is reduced
- There is better placement accuracy
- And through-put is increased

However, with any new technology there are also barriers to implementation including lack of available part types, component jams due to variability of components, and the impact of vibration on components.

To address not only the opportunities that bulk feeding has to offer but also barriers to its adoption, the IPC will hold a Bulk Feeding Summit on September 23 – 24, 1999 at the Hilton Hotel, Northbrook, IL.

The summit will feature presentations by industry leaders: Users will discuss their implementation of bulk feeding systems, component manufacturers will address component tolerances and reliability, and equipment manufacturers will outline their roadmaps for this technology.

Summit Objective

To inform/educate the industry regarding the issues associated with bulk feeding of components in electronics assembly. To attempt to come to agreement on standardized component dimensions & tolerances; standardized packaging; and a white paper report on the opportunities and barriers to bulk feeding.

Who should attend?

We have reproduced the agenda for this major meeting on the following page. As you can see this summit would be ideal for OEMs and Electronics Manufacturing Services Companies, Component Manufacturers, and Equipment Manufacturers --- anyone interested in bulk feeding and high volume placement of surface mount components.

Location for the Summit - Cost

The Summit will be held on Thursday and Friday, September 23 – 24, 1999 at the Hilton Hotel, 2855 North Milwaukee Ave., Northbrook, (Chicago) IL. To reserve a sleeping room (IPC rate of \$129) contact the Hilton Hotel at 847-480-7500.

The summit will begin at 1:00 p.m. on Thursday, September 23, 1999 and will conclude at 4:30 on Friday, September 24, 1999.

The cost to attend the Bulk Feeding Summit is \$150 for IPC member and non-members. Your registration fee includes meeting proceedings, all breaks, a reception on Thursday and lunch on Friday. To attend, we invite you to complete the registration form and return it by mail or fax (847-509-9798) to the IPC.

Bulk Feeding Summit Agenda

Hilton Hotel - Northbrook

September 23-24, 1999

Thursday, September 23, 1999

- 12:30 pm **Registration and Pre-session Coffee**
- 1:00 pm **Overview Advantages and Disadvantages of Bulk Feeding**
Mike Shomberg,
Vice President
Universal Instruments Corporation
- 1:30 pm **User Analysis of Bulk Feeding**
Tony Suppelsa,
Electrical & Manufacturing Engineer,
Motorola (Invited)
Ray Elder,
Advanced Technology Office,
Visteon Automotive Services
- 2:30 pm **Break**
- 3:00 pm **User Analysis Continues**
Sony Representative (Invited)
Ericsson Representative (Invited)
- 4:00 pm **Barriers to Implementation**
 - Standards
David W. Bergman,
Vice President,
IPC
 - Vibration impact on components
R. Komatsu,
Manager,
Sanyo
- 5:00 pm **Adjourn for Day**
- 5:30 pm **Reception**

Friday, September 24, 1999

- 8:00 am **Pre-session Coffee Break**
- 8:30 am **Equipment Status and Roadmaps**
Mike Shomberg,
Universal Instruments Corporation
Eugene Dunn,
Manager Engineering,
Panasonic Factory Automation
Hilary Sasso,
Product Manager,
Siemens Energy and Automation
Kevin Cosgrove,
Director of High Volume SMD,
Philips EMT America
Frank Cichorski, *TDK (Invited)*
- Questions and Answers**
- 10:30 am **Break**
- 11:00 am **Components Effect on Bulk Feeding**
 - Capacitors
Jim Bergenthal,
Manager, Technical Marketing,
Kemet
 - Ben Pisoni,
Mechanical Engineering Supervisor,
Murata Electronics
- 12:00 noon **Lunch**
- 1:30 pm **Components Effect on Bulk Feeding (continued)**
 - Resistors
Michael Griffith,
Product/Application Engineer,
KOA Speer Electronics
- 2:30 pm **Breakout sessions**
 - Components
 - Equipment
 - Feeders
- 3:30 pm **Results of Breakout discussions**
- 4:00 pm **Industry Actions and Summary**
- 4:30 pm **Adjourn**

Registration Form

Bulk Feeding Summit Meeting

September 23-24, 1999

Hilton Hotel, Northbrook (Chicago), IL



☐ IPC member and non-member fee \$150

Registrant's Name _____

Title _____ MailStop/Building/Dept: _____

Company _____

Mailing Address _____

City _____ State _____ Zip _____

Telephone Number (_____) _____ Fax Number (_____) _____

Email _____

METHOD OF PAYMENT:

☐ Check enclosed for \$ _____

☐ Bill P.O. # (**For IPC Members only**): _____

☐ Charge my credit card (check one): ☐ Amex ☐ MasterCard ☐ Visa ☐ Diners Club

Cardholder Name: _____ Card Number: _____

Billing Address: _____

Signature: _____ Expiration Date _____

PLEASE NOTE: Your credit card account will be debited for your registration fee. Our computer will assess the member or non-member price based on your company's current IPC membership status. No receipt will be sent.

☐ Please check here if you have a disability requiring an accommodation and call Stephen Evans at IPC (847) 790-5303 to discuss your needs.

CANCELLATION POLICY: Cancellations received one week before the start of the seminar will be refunded in full. Refunds will not be issued after the start of the program. Individuals failing to cancel will be billed for the registration fee. If the seminar is cancelled, participants will receive a full refund. Substitutions are acceptable.

Return to IPC, Department 77-3491, Chicago, IL 60678-3491 or fax (847/509-9798).